INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Application No. 10/582,588

Filing Date June 09, 2006

First Named Inventor James S. Williams et al.

Art Unit Unknown

Examiner Unknown

Attorney Docket No. DAVI258.003APC

Multiple sheets used when necessary)
SHEET 1 OF 2

1 MAN 207	/بهر /بهر		U.S. PATENT	DOCUMENTS	
	No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
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Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T¹
	10	CN 1442853	09-17-2003	Horie Michikazu		
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NON PATENT LITERATURE DOCUMENTS					
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹		
	18	P.Vettiger et al, <i>The "Millipede"-Nanotechnology Entering Data Storage</i> IEEE Transactions on Nanotechnology,1(1),pp.39-55,2002			
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Examiner Signature

Date Considered

^{*}Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

T¹ - Place a check mark in this area when an English language Translation is attached.

PTO/SB/08 Equivalent

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STATEMENT BY APPLICANT	First Named Inventor	James S. Williams et al.
STATEMENT BY ALL EIGHNI	Art Unit	Unknown
(Multiple sheets used when necessary)	Examiner	Unknown
SHEET 2 OF 2	Attorney Docket No.	DAVI258.003APC

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	22	J.S. Williams et al, Mechanical Property Characterization of Crystalline, Ion Implantation Amorphised and Annealed Relaxed Silicon with Spherical Indenters Pro. Material Research Society Symposium. 308, pp.571-6,1993			
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